

/ Descriptions

Silicon PNP transistor in a TO-18 Plastic Package.

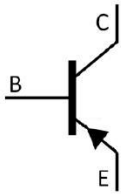
/ Features

Complement to BD139.

/ Applications

Medium power linear and switching applications.

/ Equivalent Circuit



/ Pinning



PIN1 Emitter PIN 2 Collector PIN 3 Base

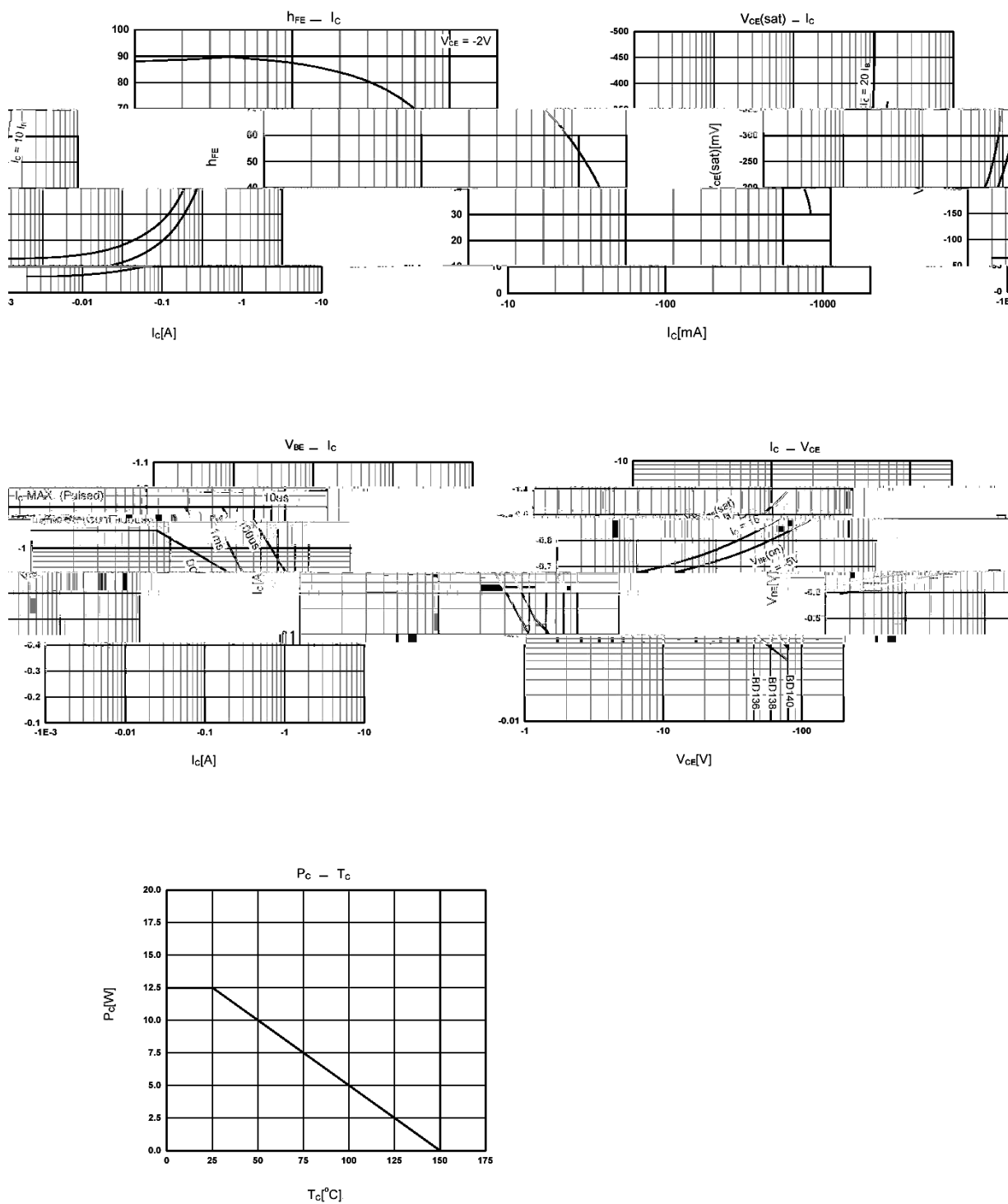
/ h_{FE} Classifications & Marking

h_{FE} Classifications Symbol	6	10	16
h_{FE} Range	40~100	63~160	100~250

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-80	V
Collector to Emitter Voltage	V_{CEO}	-80	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current - Continuous	I_C	-1.5	A
Collector Current – Continuous(Pulse)	I_{CP}	-3.0	A
Base Current - Continuous	I_B	-0.5	A
Collector Power Dissipation	P_C	1.25	W
Collector Power Dissipation	$P_C(T_c=25^{\circ}\text{C})$	12.5	W
Junction Temperature	T_J	150	$^{\circ}\text{C}$
Storage Temperature Range	T_{stg}	-55~150	$^{\circ}\text{C}$

Paramet160j954MtM9TD(1 r5218. 03895 f1 2.86 0985055a3 ()Tj95 080 1 Tf998 18.92 re95 0

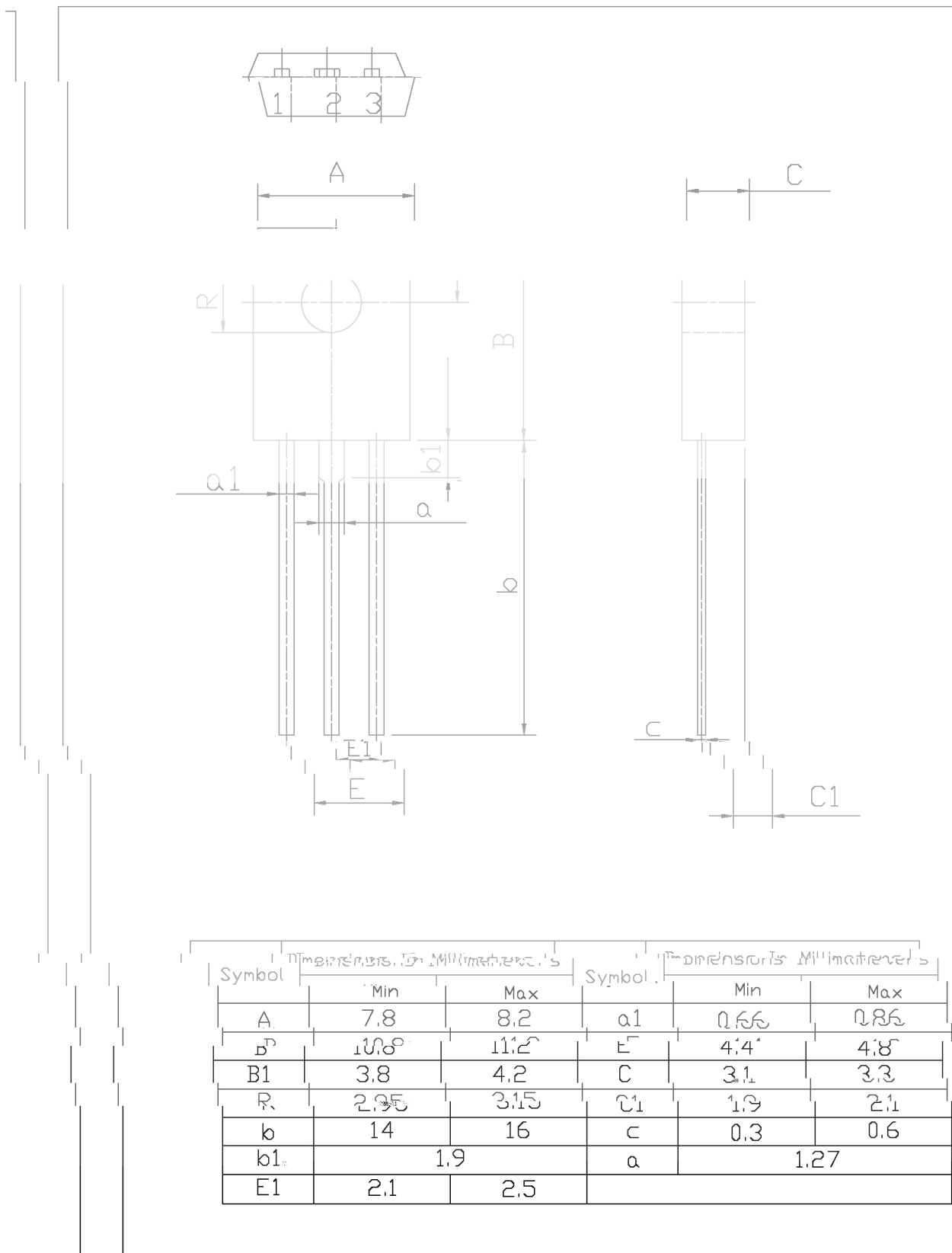
/ **Electrical Characteristic Curve**



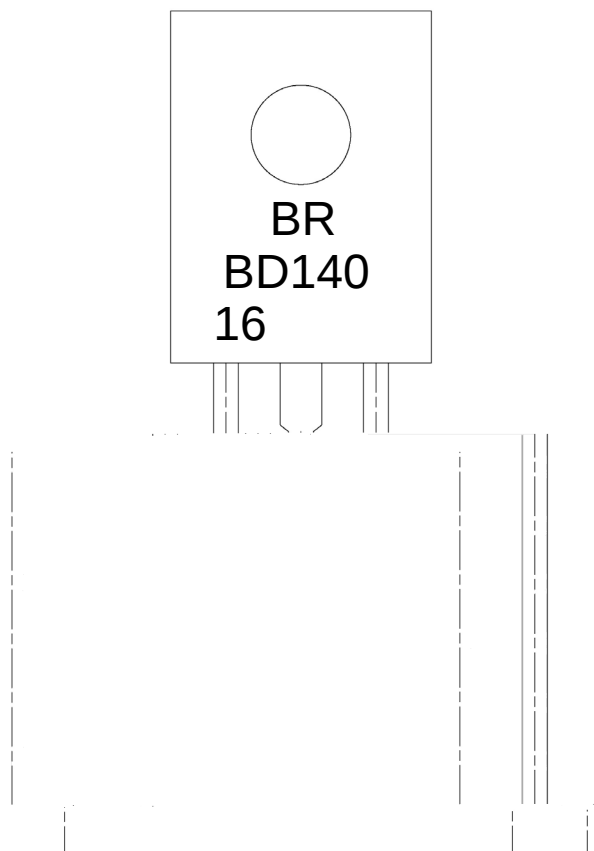
/ Package Dimensions

BU-126T

单位: mm



/ Marking Instructions



BR

h_{FE}

Note:

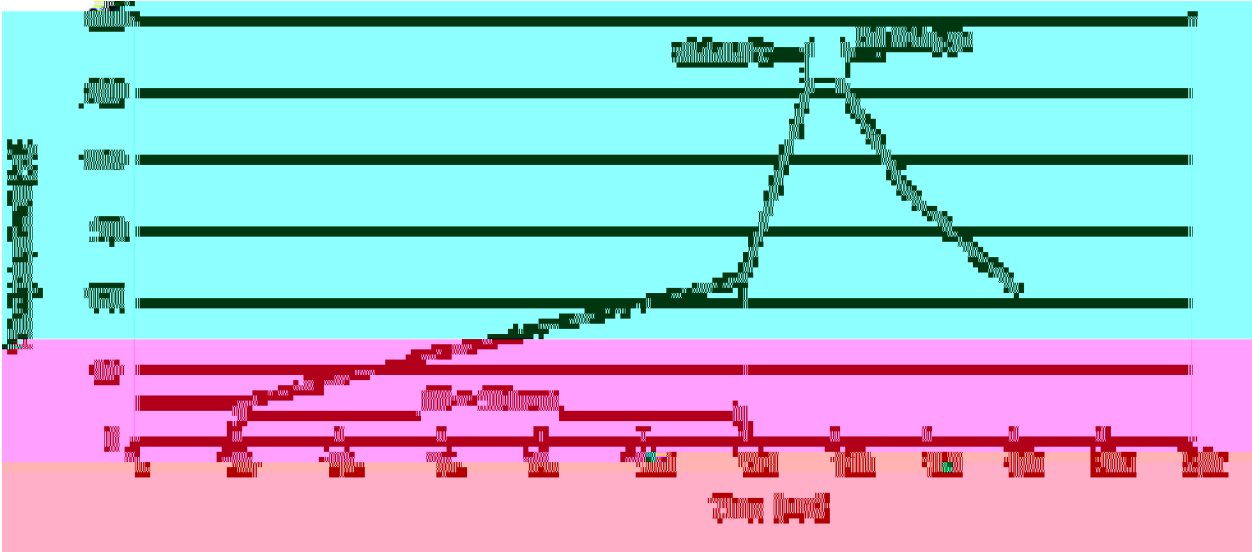
BR: Company Code

BD140: Product Type.

16: h_{FE} Classifications Symbol

***: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



- Note:
- 1

25 150

60 90sec;

1.Preheating:25~150 , Time:60~90sec.
- 2

255 5

5 0.5sec;

2.Peak Temp.:255 5 , Duration:5 0.5sec.
- 3

2 10 /sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270 5

10 1 sec.

Temp.:270±5℃

Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units 包装数量		Dimension	包装尺寸 (unit: mm ³)
封装形式	只 套管	套管 盒	只 盒	只